TO-263 ṂṂḪ N ʚ ʃ ѽ Ƶ ᶘ
N-CHANNEL MOSFET in a TO-263 Plastic Package.

Ҥ ɔ ڳ/Ầ ʜ ᵴ ỷ ȏ ɪ ɳ ғ ᵝ
X0wud 0r z Rq0Uhvlvwdqfh/idvw vzlwfklqj/ KI Surgxfw1

ᵣ ḭ Ầ ʜ ⊐ ª ℓ ᷒ Ꝗ ╚ EPV ɔ

v ̈Ω Parameter	ϒ N Symbol	̈Ω Ö Rating	D Ꮋ Unit

v ̈Ω Parameter	ϟ ᴺ Symbol	╨ ⁝ ↾ ϯ Test Conditions	ѡ ṇ Ө Min	Ɛ ȝ Ө Typ	ѡ ᶻ Ө Max	ᴅ Ꮋ Unit
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=10V V_{DS}=50V R_L=2.5Ω R_{GEN}=3Ω		27		ns
Turn-On Rise Time	t_r			20		
Turn-Off Delay Time	$t_{d(off)}$			50		
Turn-Off Fall Time	t_f			25		

/ Electrical Characteristic Curve

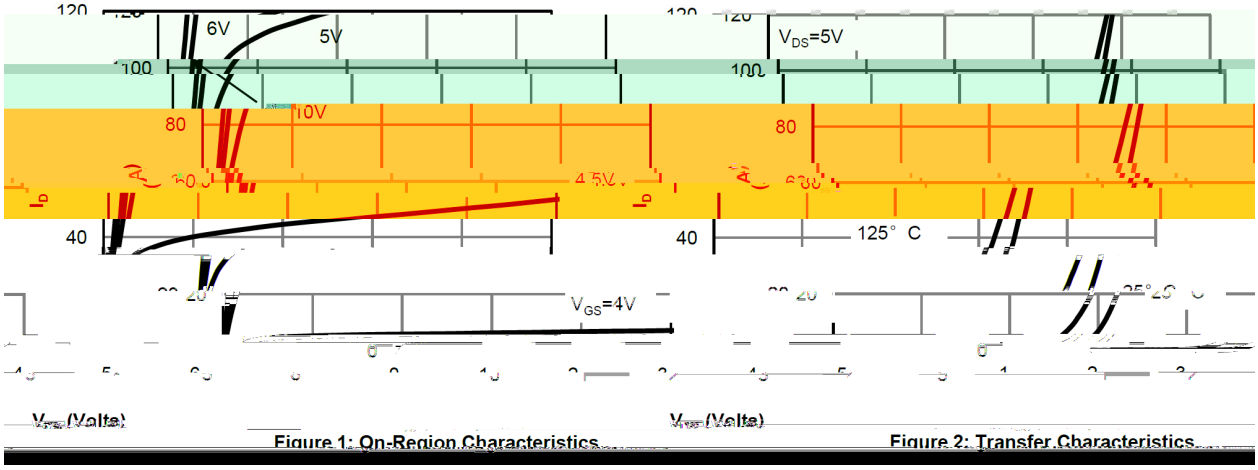
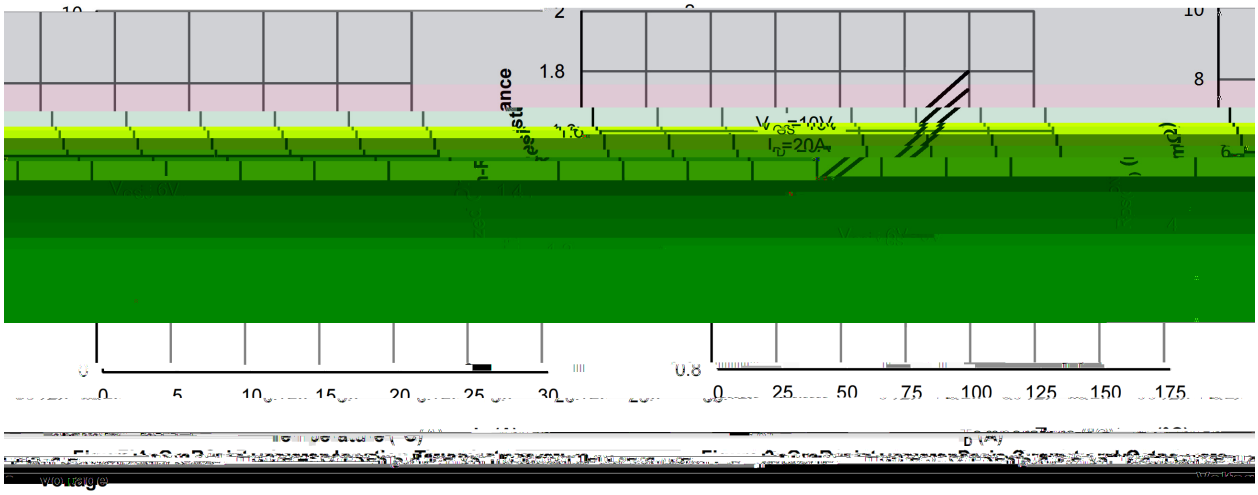


Figure 1: On-Region Characteristics

Figure 2: Transfer Characteristics



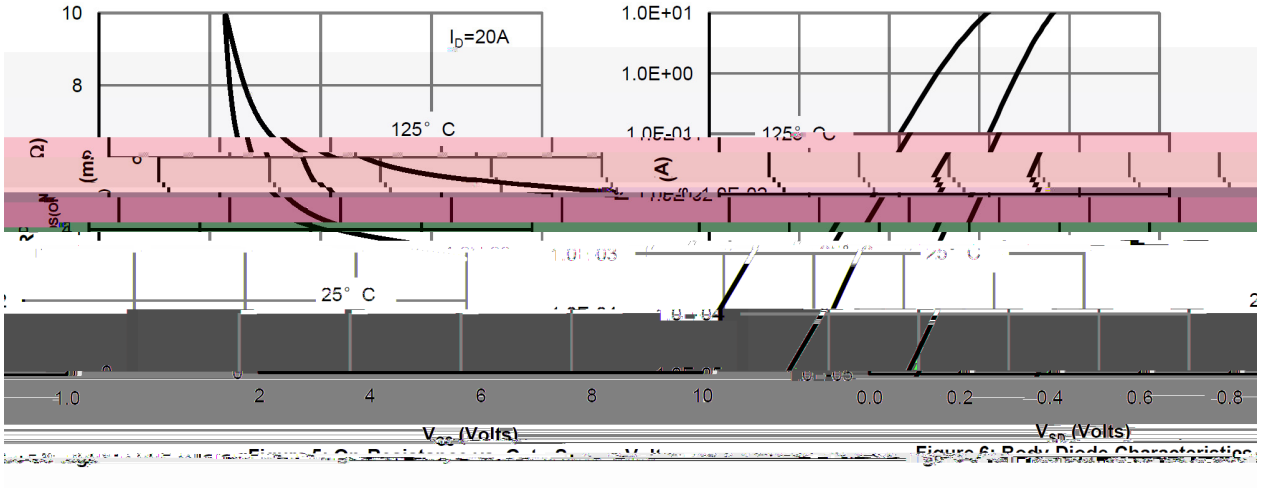
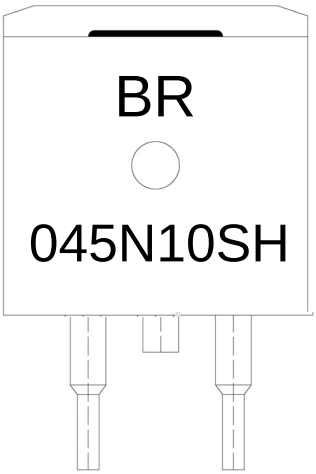


Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics

/ Marking Instructions



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EU ؤ ﺎﻣ ﺝ ﻲ ﻦﻫ

378Q43VK ؤ ﺎﻣ ﻉ ﻢ ﻦﻫ

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Note:

BR:	Company Code
045N10SH:	Product Type
****:	Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

ب ˝ χ

1 Ĺ ♬ □ ў 150 Ќ 180 ћ ı `H ڑ 60 Ќ 90sec;

2 Š Ө □ ў 245 ° 5 ћ ı `H ڑ 'Y ʌ ѭ 5 ° 0.5sec;

3 ì ˙ ٧ ˛ ɔ ѕ ў ѭ 2 Ќ 10 ћ /sec.

Note:

1.Preheating:150~180 ћ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ћ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ћ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ў χ 260 ° 5 ћ	`H ڑ χ 10 ° 1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

ɔ ` ɣ Ь / REEL

Package Type	Units					Dimension		(unit mm³)
TO-263	800	1	800	6	4,800	13 ×24	360×360×50	380×335×366

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Package Type	Units					Dimension		(unit mm³)